



30V 175°C N-CHANNEL ENHANCEMENT MODE MOSFET

Product Summary

BV _{DSS}	R _{DS(ON)} Max	I _D Max T _C = +25°C		
30V	$4m\Omega @V_{GS} = 10V$	75A		
	$7m\Omega @V_{GS} = 4.5V$	75A		

Features

- Rated to +175°C Ideal for High Ambient Temperature Environments
- High Conversion Efficiency
- Low R_{DS(ON)} Minimizes On-State Losses
- Low Input Capacitance
- Lead-Free Finish; RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability
- PPAP Capable (Note 4)

Description and Applications

This MOSFET is designed to meet the stringent requirements of automotive applications. It is qualified to AECQ101, supported by a PPAP and is ideal for use in:

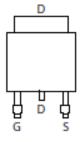
- Power Management Functions
- DC-DC Converters
- BLDC Motor control
- Reverse Polarity Protection

Mechanical Data

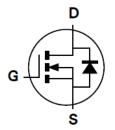
- Case: TO252 (DPAK)
- Case Material: Molded Plastic, "Green" Molding Compound.
 UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections: See Diagram
- Terminals: Matte Tin Finish. Solderable per MIL-STD-202, Method 208 (3)
- Weight: 0.315 grams (Approximate)







Pin Out Top View



Equivalent Circuit

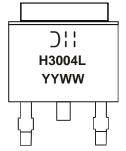
Ordering Information (Note 5)

Part Number	Case	Packaging
DMTH3004LK3Q-13	TO252 (DPAK)	2,500/Tape & Reel

Notes:

- 1. EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant. All applicable RoHS exemptions applied.
- See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. Automotive products are AEC-Q101 qualified and are PPAP capable. Refer to http://www.diodes.com/product_compliance_definitions.html.
- 5. For packaging details, go to our website at http://www.diodes.com/products/packages.html.

Marking Information



Dili=Manufacturer's Marking
H3004L = Product Type Marking Code
YYWW = Date Code Marking
YY = Last Two Digits of Year (ex: 16 = 2016)
WW = Week Code (01 to 53)



Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit		
Drain-Source Voltage	V_{DSS}	30	V		
Gate-Source Voltage			V_{GSS}	+20 -16	V
Continuous Dusin Courset V 40V	Steady State (Note 7)	$T_{C} = +25^{\circ}C$ $T_{C} = +100^{\circ}C$	I _D	75 75	А
Continuous Drain Current V _{GS} = 10V	Steady State (Note 6)	$T_A = +25^{\circ}C$ $T_A = +100^{\circ}C$	I _D	21 15	А
Pulsed Drain Current (10µs Pulse, Duty Cycle=1%)	I _{DM}	105	Α		
Maximum Continuous Body Diode Forward Current			Is	75	Α
Avalanche Current L=5mH			I _{AS}	10.7	Α
Avalanche Energy L=5mH			E _{AS}	287	mJ

Thermal Characteristics (@TA = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Total Power Dissipation (Note 7)	P_{D}	107	W
Thermal Resistance, Junction to Ambient (Note 6)	R _{θJA}	50	°C/W
Thermal Resistance, Junction to Case (Note 7)	R _{0JC}	1.4	°C/W
Operating and Storage Temperature Range	T _J , T _{STG}	-55 to +175	°C

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

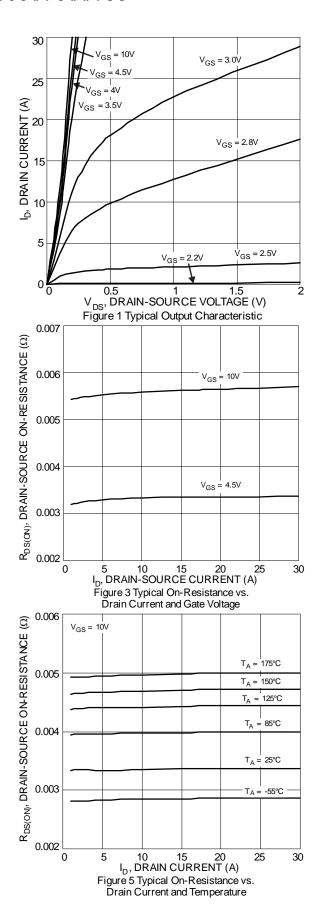
Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 8)							
Drain-Source Breakdown Voltage	BV _{DSS}	30	l		V	$V_{GS} = 0V$, $I_D = 1mA$	
Zero Gate Voltage Drain Current	I _{DSS}		1	1	μΑ	$V_{DS} = 24V, V_{GS} = 0V$	
Zero Gate Voltage Drain Current (Note 9)	I _{DSS}	1	1	10	μΑ	$V_{DS} = 24V, V_{GS} = 0V$ $T_A = +125$ °C	
Gate-Source Leakage	I _{GSS}		ı	±100	nA	$V_{GS} = +20V, V_{DS} = 0V$ $V_{GS} = -16V, V_{DS} = 0V$	
ON CHARACTERISTICS (Note 8)							
Gate Threshold Voltage	V _{GS(TH)}	1	1.7	3	V	$V_{DS} = V_{GS}$, $I_D = 250\mu A$	
Static Drain-Source On-Resistance	D	_	3.3	4	mΩ	$V_{GS} = 10V, I_D = 20A$	
Static Drain-Source On-Nesistance	R _{DS(ON)}		5.5	7	11122	$V_{GS} = 4.5V, I_D = 7A$	
Diode Forward Voltage	V_{SD}	_	0.75	1	V	$V_{GS} = 0V, I_{S} = 1A$	
DYNAMIC CHARACTERISTICS (Note 9)							
Input Capacitance	C _{ISS}		2,370	_	pF	\/ 15\/\/ 0\/	
Output Capacitance	Coss	_	1,360	-	pF $V_{DS} = 15V, V_{GS} = 0V,$ f = 1MHz		
Reverse Transfer Capacitance	C _{RSS}	_	240	_	pF		
Gate Resistance	R_G	0.15	0.6	1.5	Ω	$V_{DS} = 0V$, $V_{GS} = 0V$, $f = 1MHz$	
Total Gate Charge (V _{GS} = 4.5V)	Q_G	_	20	_	nC		
Total Gate Charge (V _{GS} = 10V)	Q_G	_	44		nC	V 45V L 20A	
Gate-Source Charge	Q _{GS}		7		nC	$V_{DS} = 15V, I_{D} = 20A$	
Gate-Drain Charge	Q_{GD}		8		nC		
Turn-On Delay Time	t _{D(ON)}		6.2		ns		
Turn-On Rise Time	t _R		4.3		ns	$V_{DD} = 15V, V_{GS} = 10V,$ $R_{L} = 0.75\Omega, R_{G} = 3\Omega, I_{D} = 20A$	
Turn-Off Delay Time	t _{D(OFF)}		21		ns		
Turn-Off Fall Time	t _F	_	8		ns		
Reverse Recovery Time	t _{RR}		25		ns	S 450 di/dt 5000/us	
Reverse Recovery Charge	Q _{RR}		37		nC	I _F =15A, di/dt=500A/μs	

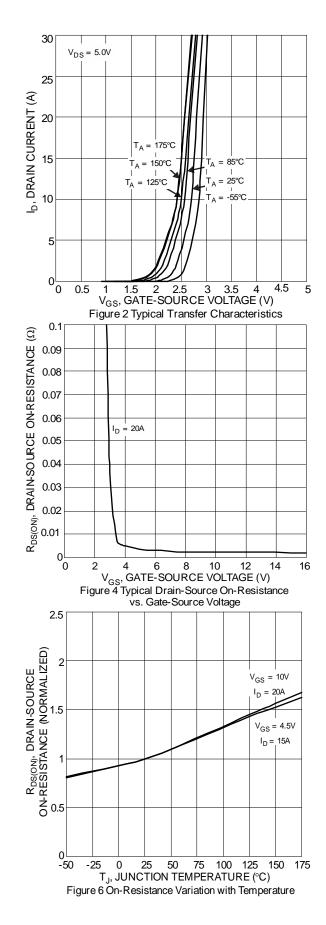
6. Device mounted on FR-4 substrate PC board, 2oz copper, with 1inch square copper plate. 7. Thermal resistance from junction to soldering point (on the exposed drain pad)

^{8.} Short duration pulse test used to minimize self-heating effect.

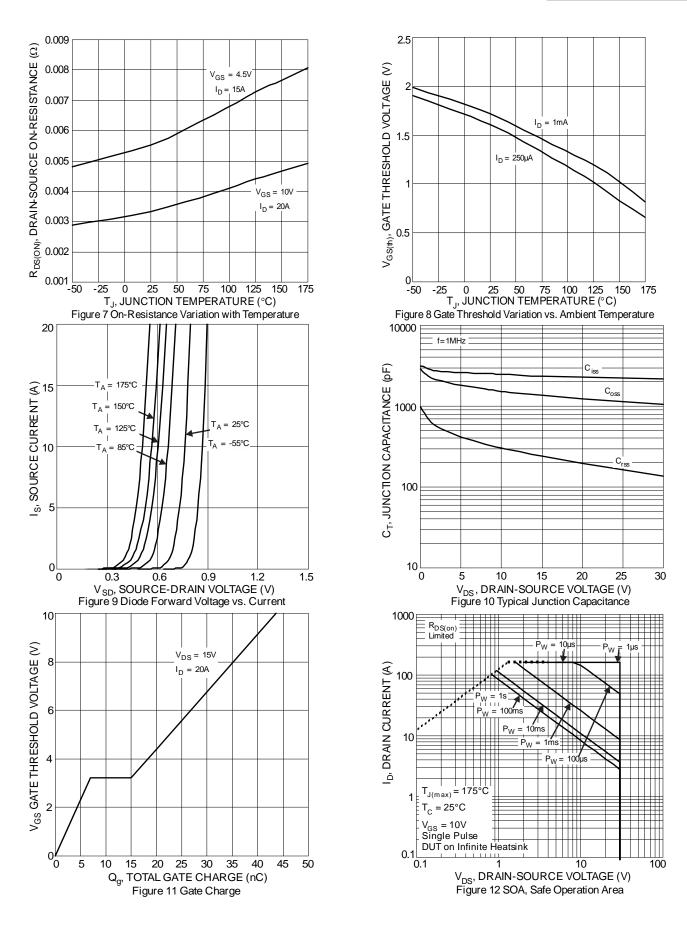
^{9.} Guaranteed by design. Not subject to product testing.



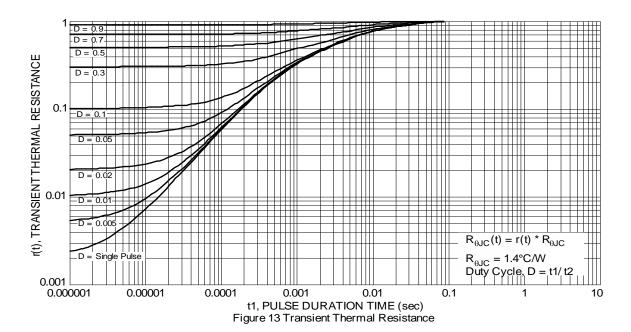










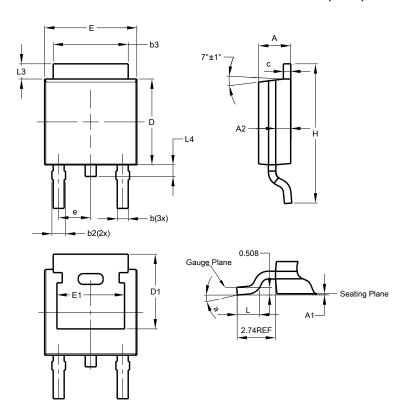




Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.

TO252 (DPAK)

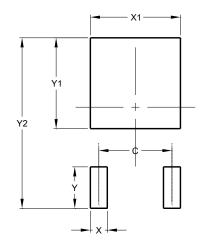


TO252 (DPAK)					
Dim	Min	Max	Тур		
Α	2.19	2.39	2.29		
A 1	0.00	0.13	0.08		
A2	0.97	1.17	1.07		
b	0.64	0.88	0.783		
b2	0.76	1.14	0.95		
b3	5.21	5.46	5.33		
С	0.45	0.58	0.531		
D	6.00	6.20	6.10		
D1	5.21	-	-		
е	_		2.286		
Е	6.45	6.70	6.58		
E1	4.32	-	-		
Н	9.40	10.41	9.91		
Г	1.40	1.78	1.59		
L3	0.88	1.27	1.08		
L4	0.64	1.02	0.83		
а	0°	10°	-		
All Dimensions in mm					

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.

TO252 (DPAK)



Dimensions	Value (in mm)		
С	4.572		
Х	1.060		
X1	5.632		
Y	2.600		
Y1	5.700		
Y2	10.700		



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